

IN THE CLAIMS

- 1 (Currently Amended). A method comprising:
positioning a wafer between a pair of rotating brushes;
providing a cleaning solution through at least one of said brushes; and
spraying a solution at the interface between said rotating brushes and said wafer
while said brushes are in contact with said wafer.
- 2 (Original). The method of claim 1 including providing a cleaning solution through the center of each of said brushes.
- 3 (Original). The method of claim 1 wherein providing a cleaning solution includes providing a solution of deionized water and a cleaning chemical.
- Claim 4 (Canceled).
- 5 (Previously Presented). The method of claim 1 including using a spray bar to spray the solution.
- 6 (Original). The method of claim 5 including spraying the deionized water at the interface between the brushes and wafers.
- 7 (Original). The method of claim 1 including providing the cleaning solution to both of said brushes.
- 8 (Original). The method of claim 1 including cleaning wafers after chemical mechanical polishing.
- 9 (Withdrawn). An apparatus comprising:
a pair of rotatable brushes to receive a wafer between said brushes; and
a cleaning solution dispenser to dispense cleaning solution from the interior of said brushes and to flow outwardly through the brushes to the brush wafer interface.

10 (Withdrawn). The apparatus of claim 9 including spray bars to spray liquid at the brush wafer interface.

11 (Withdrawn). The apparatus of claim 10 wherein said spray bars are coupled to a source of deionized water.

12 (Withdrawn). The apparatus of claim 9 including a reservoir to supply a source of cleaning solution.

13 (Withdrawn). The apparatus of claim 12 including a mixer to mix deionized water and a cleaning chemical to form the cleaning solution.

14 (Original). The apparatus of claim 9 including a pipe that provides a cleaning solution to the center of each of said brushes and ejects said cleaning solution radially outwardly through said brushes.

15 (Withdrawn). An apparatus for cleaning semiconductor wafers after chemical mechanical polishing comprising:
a pair of counter-rotating brushes to receive a wafer to be cleaned between said brushes;
a pair of spray bars to spray deionized water at the brush wafer interface; and
a cleaning solution dispenser to dispense cleaning solution from the center of each of said brushes to flow outwardly through the brushes to the brush wafer interface.

16 (Withdrawn). The apparatus of claim 15 including a mixer to mix deionized water and a cleaning chemical to form a cleaning solution.

17 (Withdrawn). The apparatus of claim 15 including a pipe that extends through each of said brushes to dispense the cleaning solution from the center of said brushes.